

ABSTRACT

A chip structure with bumps comprising: a chip and at least a bump. The chip has an active surface and at least a bonding pad that is formed on the active surface. The bump is disposed on the bonding pad, and the bump comprises a medium layer, a bump body and a bump body passivation layer. The medium layer whose material includes zinc is disposed on the bonding pad. The bump body whose material includes nickel is disposed on the medium layer. The bump body passivation layer whose material includes gold covers the bump body except for a portion of the bump body that connects to the medium layer.